Technical Specifications

Chassis Configuration	• 6U rack mount or pedestal based
Front	• Storage drive bay supports 14 hot-swap 2.5" SAS drives • Up to 6 Server Compute Modules • One Hot Swap I/O Fan Module
Rear	• One Management Module • Up to two Ethernet Switch Modules • Up to two Storage Control Modules • Four power supply bays for 3+1 redundancy • Two hot swap fan modules
Mid-Plane	• Connects subsystems to the Management Module • Designed for multiple generations of Server Compute Modules • Provides I/O for the system
Storage Control Module	• RAID: 0, 1, 1E, 5, 6, 10 • I/O: • External extended storage mini SAS port • Six internal 3GbPS SAS channels • Active-Active redundancy • Battery Backup
Ethernet Switch Module	Ports • Ten external 10/100/1000 GbE full-duplex ports • Twelve internal 1-GbE full-duplex ports Management • Port, VLAN, and Advanced Switch Configuration via the Management Module Layer 2+ features • ACL, QOS, Link Aggregation, 10K Jumbo Frame support, VLAN support, STP, and RSTP • Non-blocking I/O, wire-speed performance
Management Module	I/O • External 10/100 Ethernet port • External serial port Remote Management • Remote Media • Remote Console

Server Compute Module	Processors • Based on the Intel® 5000P series chipset and supports multi-core Intel® Xeon® processors Intel® 5000P chipset family, including: • Intel® 5000P Memory Controller Hub • Intel® 6321ESB I/O Controller Hub Memory • 8 fully-buffered DIMM (FBDIMM) slots supporting up to 32GB of memory On-board host bus adapter • LSI* 1064e SAS controller LAN • Two integrated 10/100/1000 Ethernet ports and two optional 10/100/1000 Ethernet ports via the Mezzanine Card On-board Video • Server Compute Module ATI* ES1000 video controller with 16 MB of DDR SDRAM External Connectors • Two USB 2.0 ports • Video connector Internal Connectors • One Intel® I/O Mezzanine Connector supporting an optional Mezzanine Card
Mezzanine Card	• Provides additional dual-channel Ethernet ports • Intel® Modular Server Accessory AXXGBIOMEZ
Chassis Size	• Height: 10.3 inches (6U) • Width: 17.5 inches • Depth: 28.4 inches • Weight with full configuration: 187 lbs.
Chassis Power Requirements	• Up to four 1,000-watt DC output power supply modules with 110-240V AC input • Full system configuration power requirements: 3,000 watts
Chassis Acoustical Noise Emissions	• Sound power 70 dB maximum
Chassis Environment	• Temperature operating: 10°C to 35°C 50°F to 95°F • Temperature non-operating: -40°C to 70°C -40°F to 158°F • Altitude: -30 to 1,500 m -100 to 5,000 ft
Chassis Safety	• UL60 950, CSA60 950, AS/NZS 3562, GB4943-1995, EN60 950 and 73/23/EEC, IEC 60 950, EMKO-TSE (74-SEC) 207/94, GOST-R 50377-92
Chassis Emissions	• Certified to FCC Class A; tested to CISPR 22 Class A, EN 55022 Class A and 89/336/EEC, VCCI Class A, AS/NZS 3548 Class A, ICES-003 Class A, GB9254-1998, MIC Notice 1997-42 Class A, GOST-R 29216-91 Class A, BSMI CNS13438